

250V, $170mA_{rms}/mA_{DC}$ Single-Pole, Normally Open Relay

Parameter	Rating	Units
Blocking Voltage	250	V _P
Load Current	170	mA _{rms} / mA _{DC}
On-Resistance (max)	11.5	Ω

Features

- 1500V_{rms} Input/Output Isolation
 Small 4-Pin SOP Package
- Low Drive Power Requirements
- High Reliability
- No EMI/RFI Generation
- Tape & Reel Version Available
- Flammability Rating UL 94 V-0

Applications

- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- · Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Industrial Controls

Description

The CPC1010N is a miniature single-pole, normally open (1-Form-A) solid state relay in a 4-pin SOP package that employs optically coupled MOSFET technology to provide 1500V_{rms} of input to output isolation. The efficient MOSFET switches and photovoltaic die use IXYS Integrated Circuits Division's patented OptoMOS architecture while the optically coupled output is controlled by a highly efficient infrared LED.

IXYS Integrated Circuits Division's state of the art double-molded vertical construction packaging makes the CPC1010N one of the world's smallest relays. It offers board space savings over the competitor's larger 4-pin SOP relay.

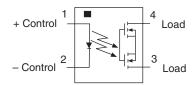
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1172007
- TUV EN 62368-1: Certificate # B 082667 0008

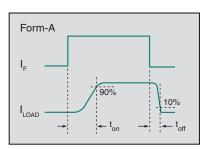
Ordering Information

Part #	Description
CPC1010N	4-Pin SOP (100/tube)
CPC1010NTR	4-Pin SOP (2000/reel)

Pin Configuration



Switching Characteristics of Normally Open Devices











Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	250	V _P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	Α
Input Power Dissipation 1	70	mW
Total Power Dissipation ²	400	mW
Isolation Voltage, Input to Output	1500	V _{rms}
Operational Temperature, Ambient	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics			'		'	
Blocking Voltage	I _L =1μΑ	V_{DRM}	250	-	-	V
Load Current						
Continuous 1	-	IL			170	mA _{rms} / mA _{DC}
Peak	t=10ms	I _{LPK}	-	-	±350	mA _P
On-Resistance ²	I _L =170mA	R _{on}	-	8.5	11.5	Ω
Off-State Leakage Current	V _L =250V _P	I _{LEAK}	-	-	1	μΑ
Switching Speeds						
Turn-On	I -Em/ \/ -10\/	t _{on}	-	-	3	ms
Turn-Off	I _F =5mA, V _L =10V	t _{off}	-	-	3	1115
Output Capacitance	I _F =0mA, V _L =20V, f=1MHz	C _{OUT}	-	9	-	pF
Input Characteristics						
Input Control Current to Activate 3	I _L =100mA	I _F	-	0.6	2	mA
Input Control Current to Deactivate	-	I _F	0.1	-	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.36	1.5	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μΑ
Input/Output Characteristics				•		
Capacitance, Input to Output	V _{IO} =0V, f=1MHz	C _{IO}	-	1	-	pF

Load current derates linearly from 170mA @ 25°C to 105mA @85°C.

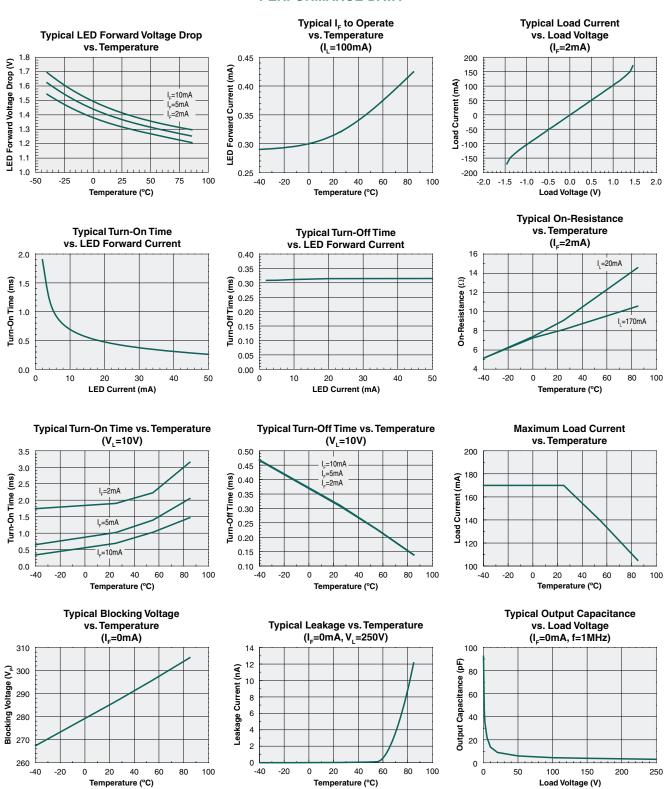
 $^{^2\,}$ Derate output power linearly 3.33 mW / °C

² Measurement taken within 1 second of on-time.

³ For applications requiring high temperature operation (greater than 60°C) a minimum LED drive current of 4mA is recommended.



PERFORMANCE DATA*



*Unless otherwise noted, data presented in these graphs is typical of device operation at 25°C.



Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL)** classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1010N	MSL 3

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

Provided in the table below is the **IPC/JEDEC J-STD-020** Classification Temperature (T_C) and the maximum dwell time the body temperature of these surface mount devices may be (T_C - 5)°C or greater. The Classification Temperature sets the Maximum Body Temperature allowed for these devices during reflow soldering processes.

Device	Classification Temperature (T _c)	Dwell Time (t _p)	Max Reflow Cycles
CPC1010N	260°C	30 seconds	3

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.



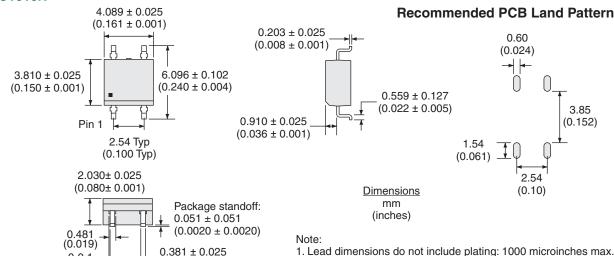






MECHANICAL DIMENSIONS



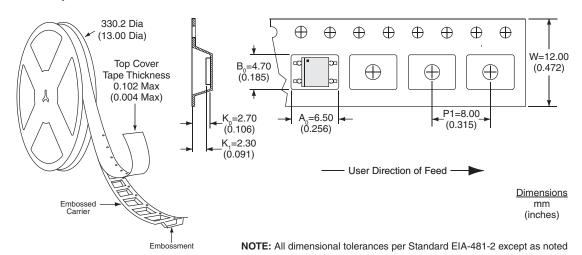


2. Controlling dimension: mm

CPC1010NTR Tape & Reel

0-0.1

(0-0.004)



For additional information please visit our website at: https://www.ixysic.com

 (0.015 ± 0.001)



Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at https://www.littelfuse.com/disclaimer-electronics.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Solid State Relays - PCB Mount category:

Click to view products by IXYS manufacturer:

Other Similar products are found below:

M86F-2W M90F-2Y G2-1A07-ST G2-1A07-TT G2-1B02-TT G2-DA06-ST 923812OCAS PLA134S DS11-1005 AQH3213J AQV212J AQY412EHAJ EFR1200480A150 901-7 LCA220 LCB110S 1618400-5 SR75-1ST AQH2213AJ AQV112KLJ AQV212AJ AQV212SXJ AQV238AD01 AQW414TS AQY221N2SYD01 AQY221R2VJ AQY275AXJ AQY414SXE01 G2-1A02-ST G2-1A03-ST G2-1A03-TT G2-1A05-ST G2-1A06-TT G2-1B01-ST G2-1B01-TT G2-1B02-ST G2-DA03-ST G2-DA03-TT G2-DA06-TT CPC1333GR 3-1617776-2 CTA2425 TLP3131(F) LBA110S LBB110S LCA110LSTR LCB126S WPPM-0626D WPPM-3526D